



## Advances in Wearable Sensors

Guest Editor:

**Dr. Le Thai Duy**

Department of Materials Science  
and Engineering, Ajou University,  
Suwon 16499, Gyeonggi-do,  
Korea

Deadline for manuscript  
submissions:

**closed (15 August 2021)**

### Message from the Guest Editor

Dear Colleagues,

Recently, advances in wearable sensors have actuated the evolution of not only personalized healthcare but also IoT applications. The barriers to practical application and usage of wearable sensors began being leveraged by the developments of deformable materials and technologies, especially manufacturing at the micro and nano-scales. However, unlike solid-state sensors, most deformable sensors, particularly stretchable ones, are yet incorporable to a broad range of advances in microelectromechanical (MEMS) that are crucial to unleash their full potential for advanced sensing devices and systems. Accordingly, this Special Issue welcomes all researchers to share breakthrough ideas and studies – including original papers and review articles – on the developments of wearable materials and technologies, including process optimization, quality assurance approaches and metrology.

- wearable sensors and technologies
- deformable materials processing
- experimental and theoretical optimizations
- MEMS-based fabrication and integration
- IoT sensing applications





an Open Access Journal by MDPI

## Editor-in-Chief

### Prof. Dr. Ai-Qun Liu

1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China  
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

## Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

## Author Benefits

**Open Access:** free for readers, with article processing charges (APC) paid by authors or their institutions.

**High Visibility:** indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

**Journal Rank:** JCR - Q2 (*Physics, Applied*) / CiteScore - Q2 (*Mechanical Engineering*)

## Contact Us

---

*Micromachines* Editorial Office  
MDPI, Grosspeteranlage 5  
4052 Basel, Switzerland

Tel: +41 61 683 77 34  
[www.mdpi.com](http://www.mdpi.com)

[mdpi.com/journal/micromachines](http://mdpi.com/journal/micromachines)  
[micromachines@mdpi.com](mailto:micromachines@mdpi.com)  
[X@micromach\\_mdpi](https://twitter.com/micromach_mdpi)